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| FORM PTO-1449<br>(Modified)  |  | U.S. Department of Commerce<br>Patent and Trademark Office |  | Attorney Docket No. JL-01301       | Serial No.: 10/680,584 |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT<br>(Use Several Sheets If Necessary) |  |  |  | Applicants: Thomas W. Kenny et al. |                        |
| (37 CFR § 1.98(b))   |  |  |  | Filing Date: October 6, 2003       | Group Art Unit: 3753   |

| FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS |    |                 |                  |                         |       |          |             |    |
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|  |    | Document Number | Publication Date | Country / Patent Office | Class | Subclass | Translation |    |
|  |    |                 |                  |                         |       |          | Yes         | No |
|  | AA | 97212126.9      | 03/04/97         | CN                      | BO1D  | 61/42    |             | X  |
|  | AB | 2000-277540     | 10/06/00         | JP                      | H01L  | 21/50    |             | X  |

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| FORM PTO-1449<br>(Modified)   |    | U.S. Department of Commerce<br>Patent and Trademark Office  |  | Attorney Docket No.: CUQL-01301    | Serial No.: 10/680,584 |
| <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b><br>(Use Several Sheets If Necessary)   |    |   |  | Applicants: Thomas W. Kenny et al. |                        |
| (37 CFR § 1.98(b))  |    |   |  | Filing Date: October 6, 2003       | Group Art Unit: 3753   |
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**INFORMATION DISCLOSURE STATEMENT BY APPLICANT**  
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Applicants: Thomas W. Kenny et al.

(37 CFR § 1.98(b))

Filing Date: October 6, 2003

Group Art Unit: 3753

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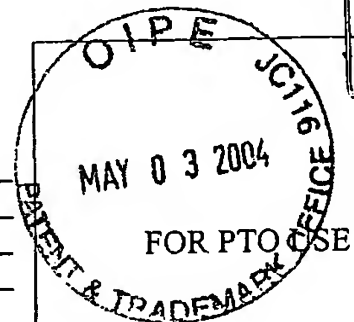
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